

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently amended) Component for a circuit board, ~~(32), having a~~ the component comprising a housing (10) on which including at least one peg (28) ~~is designed for engaging in a hole (30) in the circuit board (32), whereby;~~ the peg (28) ~~has~~ having at least one detent lug (52) which projects in the radial direction relative to the peg (28) ~~beyond its~~ the peg outer periphery; characterised in that; the detent lug (52) ~~is designed and~~ being arranged on the peg (28) such that the outer periphery of the peg (28) is smaller in the region of the detent lug (52) than the diameter of the hole (30) in the circuit board; ~~(32), whereby the outer periphery of the section of the peg (28) protruding into the hole (30) in the circuit board (32) is designed being~~ such that between the outer periphery of ~~this~~ the peg section and the inner wall of the hole (30) in the circuit board ~~(32)~~, over at least a portion of the outer periphery, there is an intermediate space with capillarity for solder, such that solder (50) situated on the surface of the circuit board ~~(32)~~ during a soldering procedure penetrates by capillary action into the intermediate space, filling it.

2. (Currently amended) Component according to claim 1, ~~characterised in that~~ wherein the detent lug (52) ~~is designed and~~ arranged on the peg (28) such that with the component placed fully on the circuit board ~~(32)~~, the detent lug (52) ~~is arranged within the hole (30) in the circuit board (32).~~

3. (Currently amended) Component according to claim ~~1 or 2~~, ~~characterised in that~~ wherein the periphery of the peg (28) in the longitudinal direction over the whole section situated in the hole (30) in the circuit board ~~(32) is designed with~~ includes at least one cut-out ~~(54).~~

4. (Currently amended) Component according to claim 3, wherein at least one of the preceding claims, characterised in that the hole (30) in the circuit board (32) is metallised.

5. (Currently amended) Component according to claim 4, wherein at least one of the preceding claims, characterised in that the peg is made of plastics.

6. (Currently amended) ~~Method for inserting a component into a circuit board designed according to at least one of the preceding claims, characterised by application of soldering paste on the circuit board round at least a portion of the periphery of the hole, placement of the component into said circuit board with the peg in the hole in said circuit board, heating of the solder arranged round the hole such that the solder penetrates by capillary action into the intermediate space with capillarity, and cooling of the solder which has penetrated into the hole, such that it hardens.~~ Component according to claim 1, wherein the periphery of the peg in the longitudinal direction over the whole section situated in the hole in the circuit board includes at least one cut-out.

7. (New) Component according to claim 1, wherein the hole in the circuit board is metallised.

8. (New) Component according to claim 1, wherein the peg is made of plastics.

9. (New) Method of inserting the component of claim 1 into the circuit board of claim 1, the method being performed by applying soldering paste on the circuit board around at least a portion of the periphery of the hole, placing the component into said circuit board with the peg in the hole in said circuit board, heating the solder around the hole such that the solder penetrates by capillary action into the intermediate space with the capillarity, and cooling the solder which has penetrated into the hole, such that the solder which has penetrated into the hole hardens.